MOSFET – Power, N-Channel, SUPERFET III, FRFET

650 V, 46 A, 65 m Ω

Description

SUPERFET III MOSFET is ON Semiconductor's brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This advanced technology is tailored to minimize conduction loss, provide superior switching performance, and withstand extreme dv/dt rate.

Consequently, SUPERFET III MOSFET is very suitable for the various power system for miniaturization and higher efficiency.

SUPERFET III FRFET MOSFET's optimized reverse recovery performance of body diode can remove additional component and improve system reliability.

Features

- 700 V @ $T_J = 150^{\circ}C$
- Typ. $R_{DS(on)} = 54 \text{ m}\Omega$
- Ultra Low Gate Charge (Typ. Q_g = 98 nC)
- Low Effective Output Capacitance (Typ. C_{oss(eff.)} = 876 pF)
- 100% Avalanche Tested
- This Device is Pb-Free and is RoHS Compliant

Applications

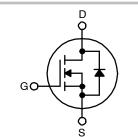
- Telecom / Server Power Supplies
- Industrial Power Supplies
- EV Charger
- USP / Solar



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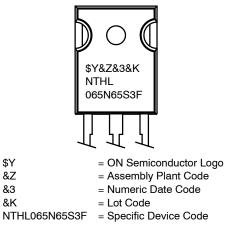
V _{DSS} R _{DS(on)} MAX		I _D MAX		
650 V	65 mΩ @ 10 V	46 A		





CASE 340CH

MARKING DIAGRAM



ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

Symbol	Parameter		NTHL065N65S3F	Unit V	
V _{DSS}	V _{DSS} Drain to Source Voltage		650		
V _{GSS}	Gate to Source Voltage	DC	±30	V	
		AC (f > 1 Hz)	±30	1	
Ι _D	Drain Current	Continuous (T _C = 25°C)	46	A	
		Continuous (T _C = 100°C)	30	1	
I _{DM}	Drain Current	Pulsed (Note 1)	115	А	
E _{AS}	Single Pulsed Avalanche En	Single Pulsed Avalanche Energy (Note 2)		mJ	
I _{AS}	Avalanche Current (Note 2) Repetitive Avalanche Energy (Note 1)		5.3	А	
E _{AR}			3.37	mJ	
dv/dt	MOSFET dv/dt		100	V/ns	
	Peak Diode Recovery dv/dt (Note 3)		50	1	
PD	Power Dissipation	$T_{\rm C} = 25^{\circ}{\rm C}$	337	W	
		Derate Above 25°C	2.7	W/°C	
T _J , T _{STG}	G Operating and Storage Temperature Range		-55 to +150	°C	
ΤL	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 Seconds		300	°C	

ABSOLUTE MAXIMUM RATINGS (T_C = 25°C unless otherwise noted)

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected. 1. Repetitive rating: pulse-width limited by maximum junction temperature.

2. $I_{AS} = 5.3 \text{ A}, R_G = 25 \Omega$, starting $T_J = 25^{\circ}\text{C}$. 3. $I_{SD} \le 23 \text{ A}, \text{ di/dt} \le 200 \text{ A/}\mu\text{s}, V_{DD} \le 400 \text{ V}, \text{ starting } T_J = 25^{\circ}\text{C}$.

THERMAL CHARACTERISTICS

Symbol	Parameter	NTHL065N65S3F	Unit	
$R_{ ext{ heta}JC}$	Thermal Resistance, Junction to Case, Max.	0.37	°C/W	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	40	°C/W	

PACKAGE MARKING AND ORDERING INFORMATION

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
NTHL065N65S3F	NTHL065N65S3F	TO-247	Tube	N/A	N/A	30 Units

ELECTRICAL CHARACTERISTICS ($T_C = 25^{\circ}C$ unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
OFF CHARACT	ERISTICS					
BV _{DSS}	Drain to Source Breakdown Voltage	V_{GS} = 0 V, I_D = 1 mA, T_J = 25°C	650	-	-	V
		$V_{GS} = 0 \text{ V}, \text{ I}_{D} = 1 \text{ mA}, \text{ T}_{J} = 150^{\circ}\text{C}$	700	-	-	V
$\Delta \text{BV}_{\text{DSS}} / \Delta \text{T}_{\text{J}}$	Breakdown Voltage Temperature Coefficient	$I_D = 15 \text{ mA}$, Referenced to 25°C	-	0.63	-	V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 650 V, V _{GS} = 0 V	-	-	10	μA
		V _{DS} = 520 V, T _C = 125°C	-	153	-	
I _{GSS}	Gate to Body Leakage Current	V_{GS} = ±30 V, V_{DS} = 0 V	-	-	±100	nA
ON CHARACTE	RISTICS					
V _{GS(th)}	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 1.3 \text{ mA}$	3.0	-	5.0	V
R _{DS(on)}	Static Drain to Source On Resistance	V _{GS} = 10 V, I _D = 23 A	-	54	65	mΩ
9fs	Forward Transconductance	V _{DS} = 20 V, I _D = 23 A	-	31	-	S
OYNAMIC CHA	RACTERISTICS				•	
C _{iss}	Input Capacitance	V _{DS} = 400 V, V _{GS} = 0 V, f = 1 MHz	-	4075	-	pF
C _{oss}	Output Capacitance		_	95	_	pF
C _{oss(eff.)}	Effective Output Capacitance	$V_{DS} = 0 V$ to 400 V, $V_{GS} = 0 V$	-	876	-	pF
C _{oss(er.)}	Energy Related Output Capacitance	V_{DS} = 0 V to 400 V, V_{GS} = 0 V	-	160	-	pF
Q _{g(tot)}	Total Gate Charge at 10V	$V_{DS} = 400 \text{ V}, \text{ I}_{D} = 23 \text{ A}, \text{ V}_{GS} = 10 \text{ V}$ (Note 4)	-	98	-	nC
Q _{gs}	Gate to Source Gate Charge		-	30	-	nC
Q _{gd}	Gate to Drain "Miller" Charge		-	38	-	nC
ESR	Equivalent Series Resistance	f = 1 MHz	-	1.5	_	Ω
WITCHING CH	IARACTERISTICS			1		
t _{d(on)}	Turn–On Delay Time	V _{DD} = 400 V, I _D = 23 A,	-	34	-	ns
t _r	Turn–On Rise Time	$V_{GS} = 10 \text{ V}, \text{ R}_{g} = 2.7 \Omega$ (Note 4)	-	31	-	ns
t _{d(off)}	Turn–Off Delay Time		-	78	-	ns
t _f	Turn–Off Fall Time		-	16	-	ns
SOURCE-DRA	IN DIODE CHARACTERISTICS	•				
I _S	Maximum Continuous Source to Drain Diode Forward Current		-	-	46	Α
I _{SM}	Maximum Pulsed Source to Drain Diode Forward Current		-	-	115	Α
V _{SD}	Source to Drain Diode Forward Voltage	V _{GS} = 0 V, I _{SD} = 23 A	-	-	1.3	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _{SD} = 23 A,	-	116	-	ns
Q _{rr}	Reverse Recovery Charge	dI _F /dt = 100 A/μs	_	488	-	nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 4. Essentially independent of operating temperature typical characteristics.

TYPICAL PERFORMANCE CHARACTERISTICS

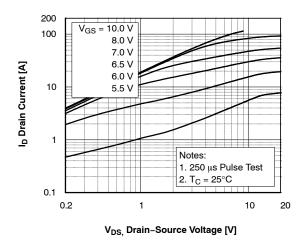
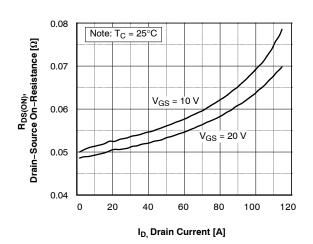
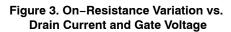


Figure 1. On-Region Characteristics





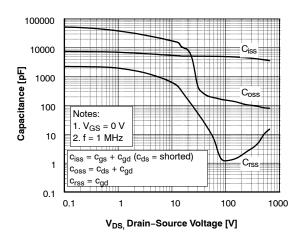


Figure 5. Capacitance Characteristics

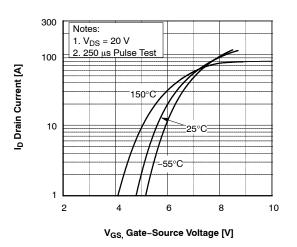
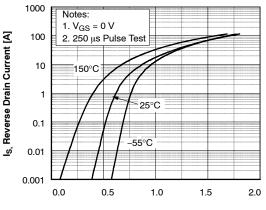


Figure 2. Transfer Characteristics



V_{SD,} Body Diode Forward Voltage [V]

Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

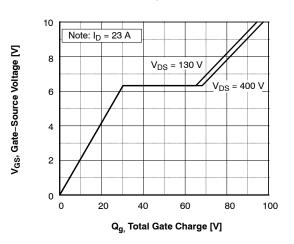
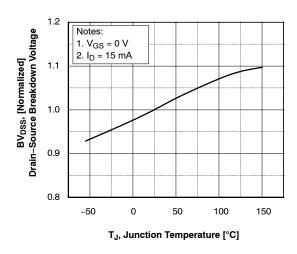


Figure 6. Gate Charge Characteristics

TYPICAL PERFORMANCE CHARACTERISTICS (Continued)





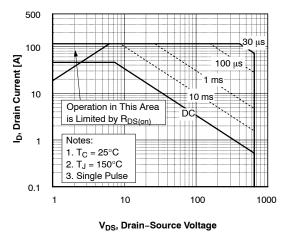


Figure 9. Maximum Safe Operating Area

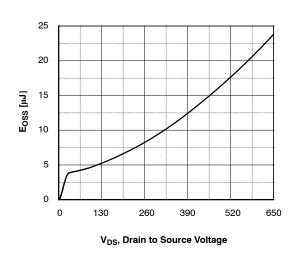


Figure 11. Eoss vs. Drain to Source Voltage

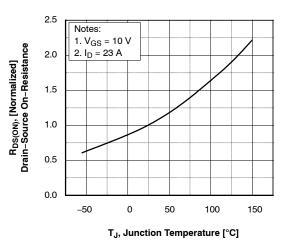


Figure 8. On–Resistance Variation vs. Temperature

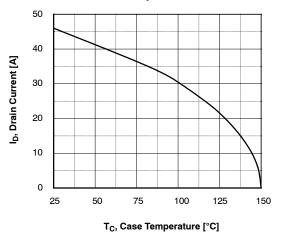


Figure 10. Maximum Drain Current vs. Case Temperature

TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

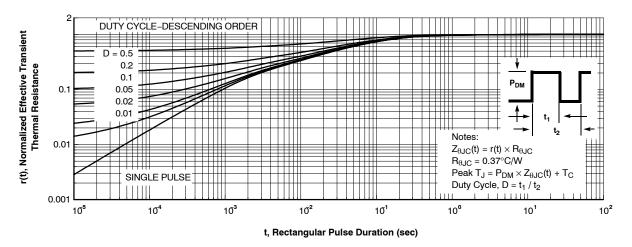
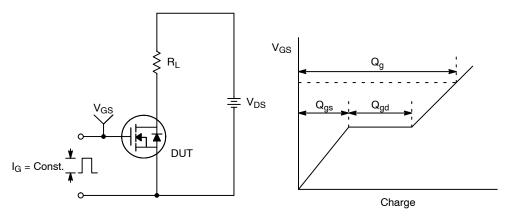


Figure 12. Transient Thermal Response Curve





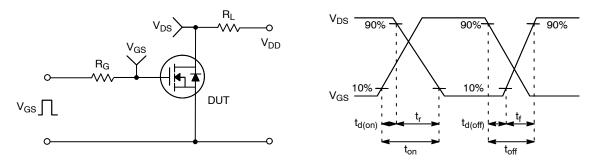


Figure 14. Resistive Switching Test Circuit & Waveforms

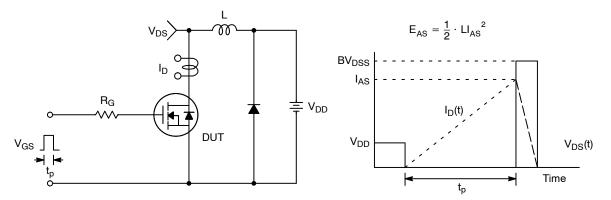


Figure 15. Unclamped Inductive Switching Test Circuit & Waveforms

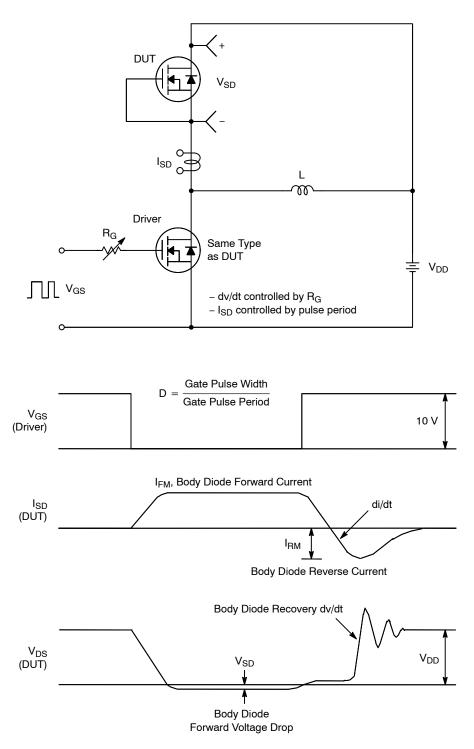
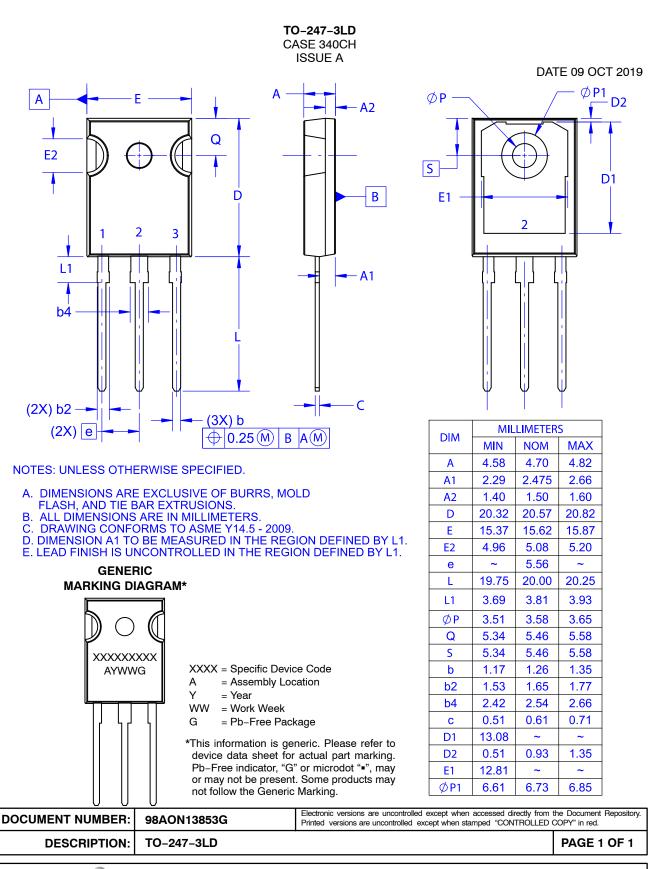


Figure 16. Peak Diode Recovery dv/dt Test Circuit & Waveforms

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